HVS series

~Sn-3.0Ag-0.5Cu lead-free solder paste~

Sn-3.0Ag-0.5Cu generally better characteristic solder paste, contributing to higher productivity and low cost for commercial production

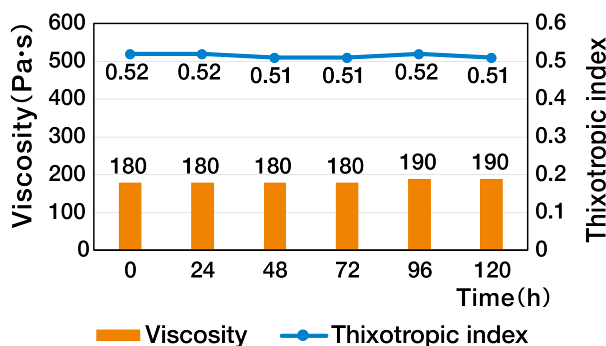
Characteristics

- Realize stable printing and soldering, minimal performance change of paste in operation
- Reduction of waste paste amount by replenishment at continuous usage

Waste paste reduction

●Small change of viscosity

Viscosity change during continuous printing

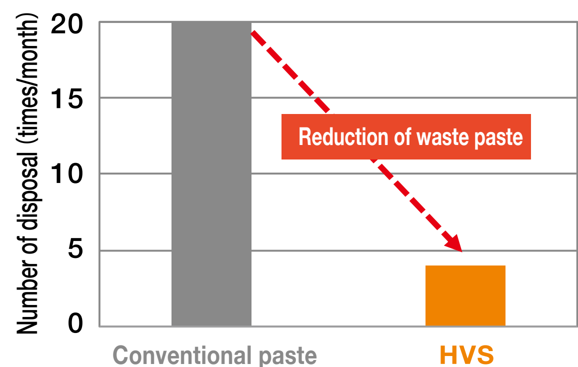


Test condition

- No aperture mask
- 50% of paste replacement,every 12 hours

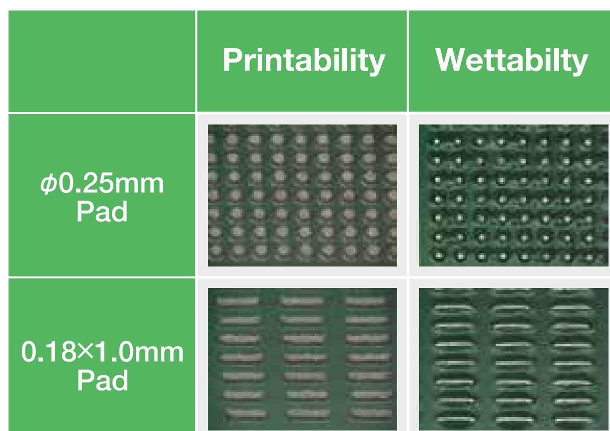
●Waste reduction to 1/5

Reduction of waste paste



Printability and wettability

●Stable printing and wetting



	Printability	Wettabilty
ϕ0.25mm Pad		
0.18×1.0mm Pad		

Test condition

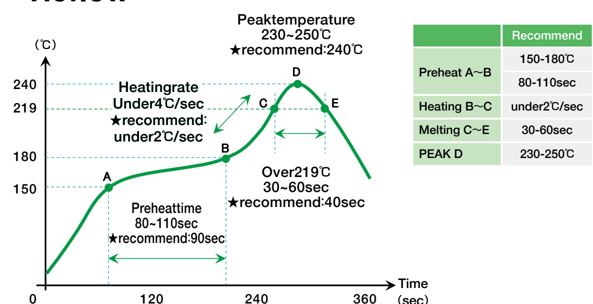
- Mask thickness : 120μm
- O_2 concentration : Air reflow

Recommended condition

●Printing

	Recommend
Squeeze type	Metal, Urethane, Plastic
Printing speed(mm/sec)	30~80
Printing pressure(×10⁻²N)	20~50
Separation speed(mm/sec)	1.0~5.0
Separation mode	Constant speed

●Reflow



	Recommend
Preheat A~B	150-180℃
	80-110sec
Heating B~C	under2℃/sec
Melting C~E	30-60sec
PEAK D	230-250℃